



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A1409-02

PCN Type: Alternate Bump and Assembly Location
Data Sheet Change: None
 No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding ASEK, Taiwan as an alternate Bump and Assembly facility.

The assembly material sets used at ASEK, Taiwan are qualified IDT materials.

There is no change to the moisture performance of this package using the assembly material sets as listed in Table 2.

Table 1: Summary of Changes

Description of Changes	From	To
Bump Location	Amkor, Taiwan	Amkor, Taiwan and ASEK, Taiwan
Assembly Location	Amkor, Philippines	Amkor, Philippines and ASEK, Taiwan

Table 2: Assembly Material Sets for the Existing Assembly & Alternate Assembly

Material Set / Assembly	Existing	Alternate
	Amkor, Philippines	ASEK, Taiwan
Die bump	Sn1.8Ag	Sn1.8Ag
Mold compound	MUF-1	KE-G1250FC-20B
Solder balls	Sn96.5/Ag3.0/Cu0.5	Sn96.5/Ag3.0/Cu0.5
Package substrate	UMTC Taiwan	UMTC Taiwan and Kinsus Taiwan



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Qualification Test Plans and Results :

Qual Plan & Results: The qualification was performed in accordance with JEDEC47 recommended tests

Qual Vehicle: 8.0mm x 13.5mm FCCSP-253

(I) ASEK with UMTC Taiwan substrate		Test Results (SS / Rej)		
Test Description	Test Method	Lot 1	Lot 2	Lot 3
* Highly Accelerated Stress Test (Vcc Max Static, 130°C/85% RH, 96Hrs)	JESD22-A110	30/0	30/0	30/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	30/0	30/0	30/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	30/0	30/0	30/0
Ball Shear Test (1000 Hrs)	JESD22-B117	5/0	5/0	5/0

Note:

* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test

(II) ASEK with KINSUS Taiwan substrate		Test Results (SS / Rej)		
Test Description	Test Method	Lot 1	Lot 2	Lot 3
* Highly Accelerated Stress Test (Vcc Max Static, 130°C/85% RH, 96Hrs)	JESD22-A110	30/0	30/0	30/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	30/0	30/0	30/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	30/0	30/0	30/0
Ball Shear Test (1000 Hrs)	JESD22-B117	5/0	5/0	5/0

Note:

* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test



Integrated Device Technology, Inc.
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ATTACHMENT II - PCN # : A1409-02

Affected Part Numbers

Part Number	Part Number
4RCD0124KC0ATG	4RCD0124KC0ATG8